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Easy Search
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L Number	Hits	Search Text	DB	Time stamp
1	92	assembly and apparatus and solder adj ball near placing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:33
2	4	assembly and apparatus and solder adj ball near placing and hopper and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:29
3	2	assembly and apparatus and solder adj ball near placing and hopper and substrate near stencil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:32
4	2	("4256532" "5880017").PN.	USPAT	2004/06/15 14:31
5	2	assembly and apparatus and solder adj ball near placing and hopper and substrate near stencil and (438/612; 438/613 ; 438/614 ; 438/615 ; 438/616 ; 257/737 ; 257/738).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:32
6	2	assembly and apparatus and hopper and substrate near stencil and (438/612; 438/613 ; 438/614 ; 438/615 ; 438/616 ; 257/737 ; 257/738).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:33
7	0	assembly and apparatus and hopper and substrate near stencil and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:33
8	247	assembly and apparatus and solder adj ball and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:34
9	0	assembly and apparatus and solder adj ball and 29/\$.cccls. and stencil and hopper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:35
10	1	assembly and apparatus and solder adj ball and 29/\$.cccls. and hopper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 14:36

11	19	assembly and apparatus and solder adj ball and hopper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB DERWENT	2004/06/15 14:36
12	1	2001-182234.NRAN.		2004/06/15 14:40

	Title	Current OR
1	System for forming contacts on a semiconductor component by aligning and attaching ferromagnetic balls	228/180.21
2	Fine pitch solder sphere placement	438/612
3	Solder-ball bonding device and method	228/246
4	Solder ball disposing apparatus, solder ball reflow apparatus, and solder ball bonding apparatus	228/41
5	Solder ball disposing apparatus, solder ball reflow apparatus, and solder ball bonding apparatus	228/41
6	Solder-ball bonding device and method	228/246
7	Apparatus for supplying solder balls	406/144
8	Method and system for forming contacts on a semiconductor component by aligning and attaching ferromagnetic balls	228/245
9	Method of making components with solder balls	438/612

	Title	Current OR
10	Machine-vision ring-reflector illumination system and method	362/247
11	Fluxless solder ball attachment process	438/615
12	Process for transferring material to semiconductor chip conductive pads using a transfer substrate	438/616
13	Preformed solder parts coated with parylene in a thickness effective to exhibit predetermined interference colors	428/212
14	Computer system with surface mount socket	439/73
15	Bottom-surface-metallurgy rework process in ceramic modules	228/119
16	Solder ball placement machine	228/41
17	Individual chip joining machine	219/85.12

	Title	Current OR
18	Fine pitch placement of solder spheres on components of assembly by moving solder spheres relative to stencil, pouring off remainder of solder spheres, removing the stencil and frame from base, and heating the components	
19	Solder ball supply smoothing appts. e.g. for semiconductor device - uses mask for positioning ball forming hole w.r.t. solder pad on circuit, with hopper dropping solder ball onto mask and squeegee pressing ball to desired height NoAbstract	